

Technical Data Sheet

MODEL NO: S776ANW4*IE

3528 Package 3.5*2.8mm Top LEDs

Features:

• Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	White	Water Clear

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

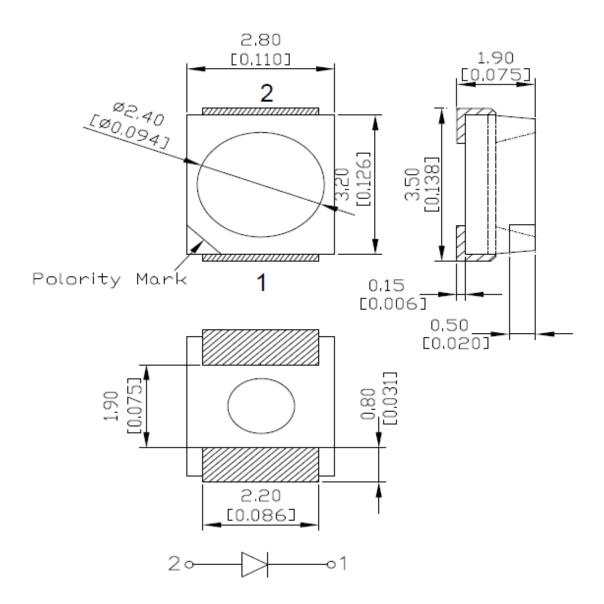
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	UIIIL
CIE Coordinates	IF=20mA	Х	0.3	0.31	0.32	
		Υ	0.31	0.32	0.33	
Forward voltage	IF=20mA	VF	3.0		3.4	V
Color Temperature	IF=20mA	VF	6000	6500	7000	K
Luminous intensity	IF=20mA	lv	2000	2500	3000	mcd
Viewing angle at 50% lv	I _F =10mA	2 0 1/2		120		Deg
Reverse current	V _R =5V	lr			10	μΑ

Absolute Maximum Ratings(Ta= 25° C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	120	mW
Forward current	lF	20	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-20 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+80	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 duty f=1kHz)	I FP	20	mA



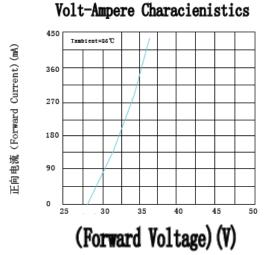
PACKAGING DIMENSIONS (mm):



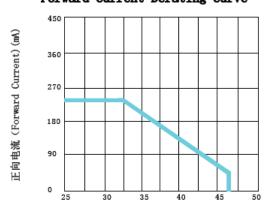


(Optical-Electrical Characteristic)



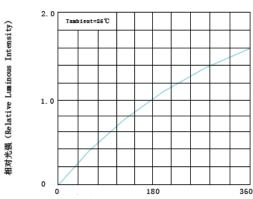


Forward Current Derating Curve



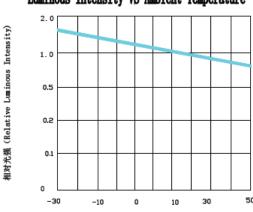
(Ambient Temperature) (C)

Relative Luminous Intensity VS Forward Current

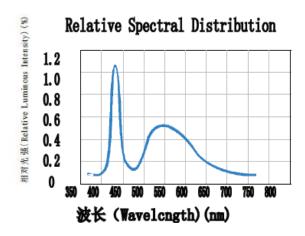


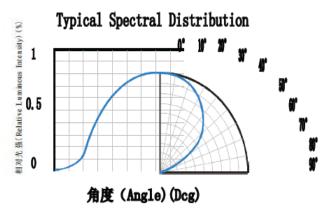
(Forward Voltage) (V)

Luminous Intensity VS Ambient Temperature



(Ambient Temperature) (°C)





Precautions For Use:

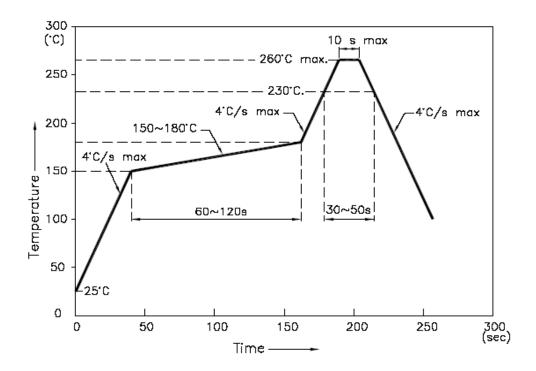
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

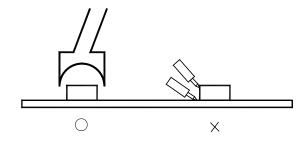


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.